**NOTES**

1. **MATERIALS:**
   - LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
   - BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QUIK-PAK FOR DETAILS.

2. **FINISH:**
   - LEAD FRAME: ELECTROLESS NICKEL PER MIL–C–26074, CLASS 1, 100 TO 300 MICROINCHES (2.5um – 7.6um) THICK.
   - GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICROINCHES (1um – 2um) THICK).
   - BODY SURFACE FINISH: VDI 21–24 (1.12–1.6 Ra).

3. **PACKAGE MISMATCH:** BODY OFFSET TO LEAD FRAME = 0.076mm MAX

4. **UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.**

5. **PACKAGE CONFORMS TO JEDEC MO–220.**

---

**SPECIFICATIONS:**

- **PART NO.:** QP-QFN28-4MM-.4MM
- **COMMENTS:**
  - BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QUIK-PAK FOR DETAILS.
  - LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
  - LEAD FRAME: ELECTROLESS NICKEL PER MIL–C–26074, CLASS 1, 100 TO 300 MICROINCHES (2.5um – 7.6um) THICK.
  - GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICROINCHES (1um – 2um) THICK).
  - BODY SURFACE FINISH: VDI 21–24 (1.12–1.6 Ra).
  - PACKAGE MISMATCH: BODY OFFSET TO LEAD FRAME = 0.076mm MAX
  - UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.
  - PACKAGE CONFORMS TO JEDEC MO–220.